C. Claims

Please cancel claims 1-15 without prejudice or disclaimer and add new claims 16-48 as follows. A complete listing of all the claims appears below; this listing replaces all earlier amendments and listings of the claims.

1. - 15. (Cancelled)

16. (New) A substrate for an ink jet head comprising:

a base plate formed with a heat-generating resistor for generating energy for discharging ink;

an electrode wiring electrically connected with said heat-generating resistor; and

a protective layer provided above said heat-generating resistor and said electrode wiring, said protective layer being constituted of a two-layered section formed by a lower layer of a TaCr alloy and an upper layer of Ta, and of a single-layered section having said lower layer,

wherein a resin construction made by resin is formed on said lower layer of said single-layered section and said upper layer of said two-layered section is provided at a position in contact with ink at least above said heat-generating resistor.

17. (New) The substrate according to claim 16, wherein said lower layer of said single-layered section fixes a flow path forming member as resin construction through an organic adhesion promoting layer.

- 18. (New) The substrate according to claim 16, wherein said lower layer of said protective layer contains Cr in an amount equal to or higher than 12 atomic %.
- 19. (New) The substrate according to claim 16, wherein said lower layer of said protective layer has an amorphous structure.
- 20. (New) The substrate according to claim 16, wherein said lower layer of said protective layer has a thickness within a range of 50 to 500 nm.
- 21. (New) The substrate according to claim 16, wherein said lower layer of said protective layer has a film stress which is at least a compression stress and is equal to or less than 1.0 x 10¹⁰ dyn/cm².
 - 22. (New) A substrate for an ink jet head comprising:
- a base plate formed with a heat-generating resistor for generating energy for discharging ink;
- an electrode wiring electrically connected with said heat-generating resistor; and
- a protective layer provided above said heat-generating resistor and said electrode wiring, and constituted of a TaCr alloy containing Cr in an amount equal to or higher than 12 atomic %, a construction made by resin being formed on said protective layer.
 - 23. (New) The substrate according to claim 22, wherein said protective layer

fixes a flow path forming member as resin construction through an organic adhesion promoting layer.

- 24. (New) The substrate according to claim 22, wherein said protective layer has an amorphous structure.
- 25. (New) The substrate according to claim 22, wherein said protective layer has a thickness within a range of 50 to 500 nm.
- 26. (New) The substrate according to claim 22, wherein said protective layer has a film stress which is at least a compression stress and is equal to or less than 1.0×10^{10} dyn/cm².
 - 27. (New) A substrate for an ink jet head comprising:
- a base plate formed with a heat-generating resistor for generating energy for discharging ink;
- an electrode wiring electrically connected with said heat-generating resistor; and
- a protective layer provided above said heat-generating resistor and said electrode wiring, and having a film stress which is at least a compression stress and is equal to or less than 1.0×10^{10} dyn/cm², a construction made by resin being formed on said protective layer.
 - 28. (New) The substrate according to claim 27, wherein said protective layer

fixes a flow path forming member as resin construction through an organic adhesion promoting layer.

- 29. (New) The substrate according to claim 27, wherein said protective layer has an amorphous structure.
- 30. (New) The substrate according to claim 27, wherein said protective layer has a thickness within a range of 50 to 500 nm.
 - 31. (New) An ink jet head comprising:
- a construction made by a resin for forming a discharge port for discharging ink, and an ink flow path communicated with said discharge port and having a portion effecting the ink with thermal energy for discharging ink;
- a base plate formed with a heat-generating resistor for generating energy for discharging ink;
- an electrode wiring provided on said base plate and electrically connected with said heat-generating resistor; and
- a protective layer provided above said heat-generating resistor and said electrode wiring, said protective layer being constituted of a two-layered section formed by a lower layer of a TaCr alloy and an upper layer of Ta, and of a single-layered section having said lower layer,

wherein a resin construction made by resin is formed on said lower layer of said single-layered section and said upper layer of said two-layered section is provided at a position in contact with ink at least above said heat-generating resistor.

- 32. (New) The ink jet head according to claim 31, wherein said lower layer of said single-layered section fixes a flow path forming member as resin construction through an organic adhesion promoting layer.
- 33. (New) The ink jet head according to claim 31, wherein said lower layer of said protective layer contains Cr in an amount equal to or higher than 12 atomic %.
- 34. (New) The ink jet head according to claim 31, wherein said lower layer of said protective layer has an amorphous structure.
- 35. (New) The ink jet head according to claim 31, wherein said lower layer of said protective layer has a thickness within a range of 50 to 500 nm.
- 36. (New) The ink jet head according to claim 31, wherein said lower layer of said protective layer has a film stress which is at least a compression stress and is equal to or less than 1.0×10^{10} dyn/cm².
 - 37. (New) An ink jet head comprising:
- a construction made by a resin for forming a discharge port for discharging ink, and an ink flow path communicated with said discharge port and having a portion effecting the ink with thermal energy for discharging ink:
- a base plate formed with a heat-generating resistor for generating energy for discharging ink;

an electrode wiring provided on said base plate and electrically connected

with said heat-generating resistor; and

a protective layer provided above said heat-generating resistor and said electrode wiring, and constituted of a TaCr alloy containing Cr in an amount equal to or higher than 12 atomic %, a construction made by resin being formed on said protective layer.

- 38. (New) The ink jet head according to claim 37, wherein said protective layer fixes a flow path forming member as resin construction through an organic adhesion promoting layer.
- 39. (New) The ink jet head according to claim 37, wherein said protective layer has an amorphous structure.
- 40. (New) The ink jet head according to claim 37, wherein said protective layer has a thickness within a range of 50 to 500 nm.
- 41. (New) The ink jet head according to claim 37, wherein said protective layer has a film stress which is at least a compression stress and is equal to or less than 1.0 x 10^{10} dyn/cm².
 - 42. (New) An ink jet head comprising:

a construction made by a resin for forming a discharge port for discharging ink, and an ink flow path communicated with said discharge port and having a portion effecting the ink with thermal energy for discharging ink:

a base plate formed with a heat-generating resistor for generating energy for discharging ink;

an electrode wiring provided on said base plate and electrically connected with said heat-generating resistor; and

a protective layer provided above said heat-generating resistor and said electrode wiring, and having a film stress which is at least a compression stress and is equal to or less than 1.0×10^{10} dyn/cm², a construction made by resin being formed on said protective layer.

- 43. (New) The ink jet head according to claim 42, wherein said protective layer fixes a flow path forming member as resin construction through an organic adhesion promoting layer.
- 44. (New) The ink jet head according to claim 42, wherein said protective layer has an amorphous structure.
- 45. (New) The ink jet head according to claim 42, wherein said protective layer has a thickness within a range of 50 to 500 nm.
- 46. (New) A producing method for an ink jet head including a construction made by a resin for forming a discharge port for discharging ink, and an ink flow path communicated with said discharge port and having a portion effecting the ink with thermal energy for discharging ink; a base plate formed with a heat-generating resistor for generating energy for discharging ink; an electrode wiring provided on said base plate and

electrically connected with said heat-generating resistor; and a protective layer provided above said heat-generating resistor and said electrode wiring, said protective layer being constituted of a two-layered section formed by a lower layer of a TaCr alloy and an upper layer of Ta, and of a single-layered section having said lower layer, wherein a resin construction made by resin is formed on said lower layer of said single-layered section and said upper layer of said two-layered section is provided at a position in contact with ink at least above said heat-generating resistor, comprising the steps of:

forming a protective layer in which a Ta layer is laminated on a layer formed by a TaCr alloy;

selectively patterning said Ta layer and selectively removing said Ta layer;

forming the ink flow path in a portion where the layer formed by said TaCr alloy is exposed by said removing.

47. (New) A producing method for an ink jet head including a construction made by a resin for forming a discharge port for discharging ink, and an ink flow path communicated with said discharge port and having a portion effecting the ink with thermal energy for discharging ink; a base plate formed with a heat-generating resistor for generating energy for discharging ink; an electrode wiring provided on said base plate and electrically connected with said heat-generating resistor; and a protective layer provided above said heat-generating resistor and said electrode wiring, and constituted of a TaCr alloy containing Cr in an amount equal to or higher than 12 atomic %, a construction made by resin being formed on said protective layer, comprising the steps of:

forming a protective layer in which a Ta layer is laminated on a layer formed by a TaCr alloy;

selectively patterning said Ta layer and selectively removing said Ta layer;

forming the ink flow path in a portion where the layer formed by said TaCr alloy is exposed by said removing.

48. (New) A producing method for an ink jet head including a construction made by a resin for forming a discharge port for discharging ink, and an ink flow path communicated with said discharge port and having a portion effecting the ink with thermal energy for discharging ink; a base plate formed with a heat-generating resistor for generating energy for discharging ink; an electrode wiring provided on said base plate and electrically connected with said heat-generating resistor; and a protective layer provided above said heat-generating resistor and said electrode wiring, and having a film stress which is at least a compression stress and is equal to or less than 1.0×10^{10} dyn/cm², a construction made by resin being formed on said protective layer, comprising the steps of:

forming a protective layer in which a Ta layer is laminated on a layer formed by a TaCr alloy;

selectively patterning said Ta layer and selectively removing said Ta layer;

forming the ink flow path in a portion where the layer formed by said TaCr alloy is exposed by said removing.